

+3.3V Programmable LVDS Transmitter 24-Bit Flat Panel Display Link-87.5 MHz

Check for Samples: [DS90C385A](#)

FEATURES

- Pin-to-Pin Compatible to DS90C383, DS90C383A and DS90C385
- No Special Start-Up Sequence Required between Clock/Data and /PD Pins. Input Signals (Clock and Data) can be Applied Either Before or After the Device is Powered.
- Support Spread Spectrum Clocking up to 100kHz Frequency Modulation and Deviations of $\pm 2.5\%$ Center Spread or -5% Down Spread
- "Input Clock Detection" Feature Will Pull All LVDS Pairs to Logic Low When Input Clock is Missing and When /PD Pin is Logic High
- 18 to 87.5 MHz Shift Clock Support
- Tx Power Consumption < 147 mW (typ) at 87.5MHz Grayscale
- Tx Power-Down Mode < 60 μ W (typ)
- Supports VGA, SVGA, XGA, SXGA(Dual Pixel), SXGA+(Dual Pixel), UXGA(Dual Pixel).
- Narrow Bus Reduces Cable Size and Cost
- Up to 2.45 Gbps Throughput
- Up to 306.25Megabyte/sec Bandwidth
- 345 mV (typ) Swing LVDS Devices for Low EMI
- PLL Requires No External Components
- Compliant to TIA/EIA-644 LVDS standard
- Low Profile 56-lead TSSOP Package

DESCRIPTION

The DS90C385A is a pin to pin compatible replacement for DS90C383, DS90C383A and DS90C385. The DS90C385A has additional features and improvements making it an ideal replacement for DS90C383, DS90C383A and DS90C385. family of LVDS Transmitters.

The DS90C385A transmitter converts 28 bits of LVCMOS/LVTTL data into four LVDS (Low Voltage Differential Signaling) data streams. A phase-locked transmit clock is transmitted in parallel with the data streams over the fifth LVDS link. Every cycle of the transmit clock 28 bits of input data are sampled and transmitted. At a transmit clock frequency of 87.5 MHz, 24 bits of RGB data and 3 bits of LCD timing and control data (FPLINE, FPFRAME, DRDY) are transmitted at a rate of 612.5Mbps per LVDS data channel. Using a 87.5 MHz clock, the data throughput is 306.25Mbytes/sec. This transmitter can be programmed for Rising edge strobe or Falling edge strobe through a dedicated pin. A Rising edge or Falling edge strobe transmitter will interoperate with a Falling edge strobe FPDLink Receiver without any translation logic.

This chipset is an ideal means to solve EMI and cable size problems associated with wide, high-speed TTL interfaces with added Spread Spectrum Clocking support.

Block Diagram

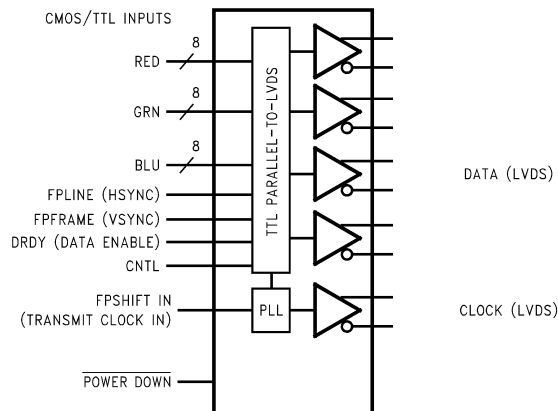


Figure 1. DS90C385A



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TRI-STATE is a registered trademark of Texas Instruments.
All other trademarks are the property of their respective owners.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V_{CC})		-0.3V to +4V
CMOS/TTL Input Voltage		-0.5V to ($V_{CC} + 0.3V$)
LVDS Driver Output Voltage		-0.3V to ($V_{CC} + 0.3V$)
LVDS Output Short Circuit Duration		Continuous
Junction Temperature		+150°C
Storage Temperature		-65°C to +150°C
Lead Temperature (Soldering, 4 seconds)		+260°C
Maximum Package Power Dissipation Capacity at 25°C	TSSOP Package	1.63 W
Package Derating		12.5 mW/°C above +25°C
ESD Rating	HBM, 1.5k Ω , 100pF	7kV
	EIAJ, 0 Ω , 200 pF	500V
Latch Up Tolerance at 25°C		± 100 mA

- (1) "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be ensured. They are not meant to imply that the device should be operated at these limits. The tables of "Electrical Characteristics" specify conditions for device operation.

Recommended Operating Conditions

	Min	Nom	Max	Unit
Supply Voltage (V_{CC})	3.0	3.3	3.6	V
Operating Free Air Temperature (T_A)	-10	+25	+70	°C
Supply Noise Voltage (V_{CC})			200	mV _{PP}
TxCLKIN frequency	18		87.5	MHz

Electrical Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
LVCMOS/LVTTL DC SPECIFICATIONS							
V _{IH}	High Level Input Voltage		2.0		V _{CC}	V	
V _{IL}	Low Level Input Voltage		0		0.8	V	
V _{CL}	Input Clamp Voltage	I _{CL} = -18 mA		-0.79	-1.5	V	
I _{IN}	Input Current	V _{IN} = 0.4V, 2.5V or V _{CC}		+1.8	+10	μA	
		V _{IN} = GND	-10	0		μA	
LVDS DC SPECIFICATIONS							
V _{OD}	Differential Output Voltage	R _L = 100Ω	250	345	450	mV	
ΔV _{OD}	Change in V _{OD} between complimentary output states				35	mV	
V _{OS}	Offset Voltage ⁽¹⁾		1.13	1.25	1.38	V	
ΔV _{OS}	Change in V _{OS} between complimentary output states				35	mV	
I _{OS}	Output Short Circuit Current	V _{OUT} = 0V, R _L = 100Ω		-3.5	-5	mA	
I _{OZ}	Output TRI-STATE® Current	Power Down = 0V, V _{OUT} = 0V or V _{CC}		±1	±10	μA	
TRANSMITTER SUPPLY CURRENT							
ICCTW	Transmitter Supply Current, Worst Case	R _L = 100Ω, C _L = 5 pF, Worst Case Pattern (Figure 2 Figure 4) "Typ" values are given for V _{CC} = 3.6V and T _A = +25°C, "Max" values are given for V _{CC} = 3.6V and T _A = -10°C	f = 25 MHz		31	45	mA
			f = 40 MHz		37	50	mA
			f = 65 MHz		48	60	mA
			f = 87.5 MHz		55	65	mA
ICCTG	Transmitter Supply Current, 16 Grayscale	R _L = 100Ω, C _L = 5 pF, 16 Grayscale Pattern (Figure 3 Figure 4) "Typ" values are given for V _{CC} = 3.6V and T _A = +25°C, "Max" values are given for V _{CC} = 3.6V and T _A = -10°C	f = 25 MHz		29	40	mA
			f = 40 MHz		33	45	mA
			f = 65 MHz		39	50	mA
			f = 87.5 MHz		44	55	mA
ICCTZ	Transmitter Supply Current, Power Down	Power Down = Low Driver Outputs in TRI-STATE® under Power Down Mode		17	150	μA	

(1) V_{OS} previously referred as V_{CM} .

Recommended Transmitter Input Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified

Symbol	Parameter	Min	Typ	Max	Unit
TCIT	TxCLK IN Transition Time (Figure 6)	1.0		6.0	ns
TCIP	TxCLK IN Period (Figure 7)	11.42	T	55.55	ns
TCIH	TxCLK IN High Time (Figure 7)	0.35T	0.5T	0.65T	ns
TCIL	TxCLK IN Low Time (Figure 7)	0.35T	0.5T	0.65T	ns
TXIT	TxIN , and PWR DOWN pin Transition Time	1.5		6.0	ns
TXPD	Minimum pulse width for PWR DOWN pin signal	1			us

Transmitter Switching Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified

Symbol	Parameter		Min	Typ	Max	Unit
LLHT	LVDS Low-to-High Transition Time (Figure 5)			0.75	1.4	ns
LHLT	LVDS High-to-Low Transition Time (Figure 5)			0.75	1.4	ns
TPPos0	Transmitter Output Pulse Position (Figure 13) ⁽¹⁾	f = 25MHz	-0.45	0	+0.45	ns
TPPos1	Transmitter Output Pulse Position		5.26	5.71	6.16	ns
TPPos2	Transmitter Output Pulse Position		10.98	11.43	11.88	ns
TPPos3	Transmitter Output Pulse Position		16.69	17.14	17.59	ns
TPPos4	Transmitter Output Pulse Position		22.41	22.86	23.31	ns
TPPos5	Transmitter Output Pulse Position		28.12	28.57	29.02	ns
TPPos6	Transmitter Output Pulse Position		33.84	34.29	34.74	ns
TPPos0	Transmitter Output Pulse Position (Figure 13) ⁽¹⁾	f = 40 MHz	-0.25	0	+0.25	ns
TPPos1	Transmitter Output Pulse Position		3.32	3.57	3.82	ns
TPPos2	Transmitter Output Pulse Position		6.89	7.14	7.39	ns
TPPos3	Transmitter Output Pulse Position		10.46	10.71	10.96	ns
TPPos4	Transmitter Output Pulse Position		14.04	14.29	14.54	ns
TPPos5	Transmitter Output Pulse Position		17.61	17.86	18.11	ns
TPPos6	Transmitter Output Pulse Position		21.18	21.43	21.68	ns
TPPos0	Transmitter Output Pulse Position (Figure 13) ⁽¹⁾	f = 65 MHz	-0.20	0	+0.20	ns
TPPos1	Transmitter Output Pulse Position		2.00	2.20	2.40	ns
TPPos2	Transmitter Output Pulse Position for Bit 2		4.20	4.40	4.60	ns
TPPos3	Transmitter Output Pulse Position for Bit 3		6.39	6.59	6.79	ns
TPPos4	Transmitter Output Pulse Position		8.59	8.79	8.99	ns
TPPos5	Transmitter Output Pulse Position		10.79	10.99	11.19	ns
TPPos6	Transmitter Output Pulse Position		12.99	13.19	13.39	ns
TPPos0	Transmitter Output Pulse Position (Figure 13) ⁽¹⁾	f = 87.5 MHz	-0.20	0	+0.20	ns
TPPos1	Transmitter Output Pulse Position		1.48	1.68	1.88	ns
TPPos2	Transmitter Output Pulse Position		3.16	3.36	3.56	ns
TPPos3	Transmitter Output Pulse Position		4.84	5.04	5.24	ns
TPPos4	Transmitter Output Pulse Position		6.52	6.72	6.92	ns
TPPos5	Transmitter Output Pulse Position		8.20	8.40	8.60	ns
TPPos6	Transmitter Output Pulse Position		9.88	10.08	10.28	ns
TSTC	Required TxIN Setup to TxCLK IN (Figure 7) at 85MHz		2.5			ns
THTC	Required TxIN Hold to TxCLK IN (Figure 7) at 87.5 MHz		0.5			ns
TCCD	TxCLK IN to TxCLK OUT Delay. Measure from TxCLK IN edge to immediately crossing point of differential TxCLK OUT by following the positive TxCLK OUT. 50% duty cycle input clock is assumed. (Figure 8)	T _A = -10°, and 87.5MHz for "Min", T _A = 70°, and 25MHz for "Max", V _{CC} = 3.6V, R_FB pin = VCC	3.086		7.211	ns
	Measure from TxCLK IN edge to immediately crossing point of differential TxCLK OUT by following the positive TxCLK OUT. 50% duty cycle input clock is assumed. (Figure 9)	T _A = -10°, and 87.5MHz for "Min", T _A = 70°, and 25MHz for "Max", V _{CC} = 3.6V, R_FB pin = GND	2.868		6.062	ns

(1) The Minimum and Maximum Limits are based on statistical analysis of the device performance over process, voltage, and temperature ranges. This parameter is functionality tested only on Automatic Test Equipment (ATE).

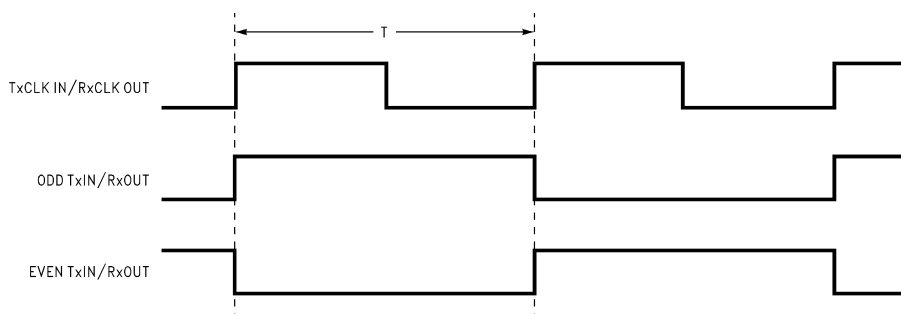
Transmitter Switching Characteristics (continued)

Over recommended operating supply and temperature ranges unless otherwise specified

Symbol	Parameter	Min	Typ	Max	Unit
SSCG	Spread Spectrum Clock support; Modulation frequency with a linear profile. ⁽²⁾	f = 25 MHz	100kHz ±2.5%/-5%		
		f = 40 MHz	100kHz ±2.5%/-5%		
		f = 65 MHz	100kHz ±2.5%/-5%		
		f = 87.5 MHz	100kHz ±2.5%/-5%		
TPLLS	Transmitter Phase Lock Loop Set (Figure 10)			10	ms
TPDD	Transmitter Power Down Delay (Figure 12)			100	ns

- (2) Care must be taken to ensure TSTC and THTC are met so input data are sampling correctly. This SSCG parameter only shows the performance of tracking Spread Spectrum Clock applied to TxCLK IN pin, and reflects the result on TxCLKOUT+ and TxCLKOUT- pins.

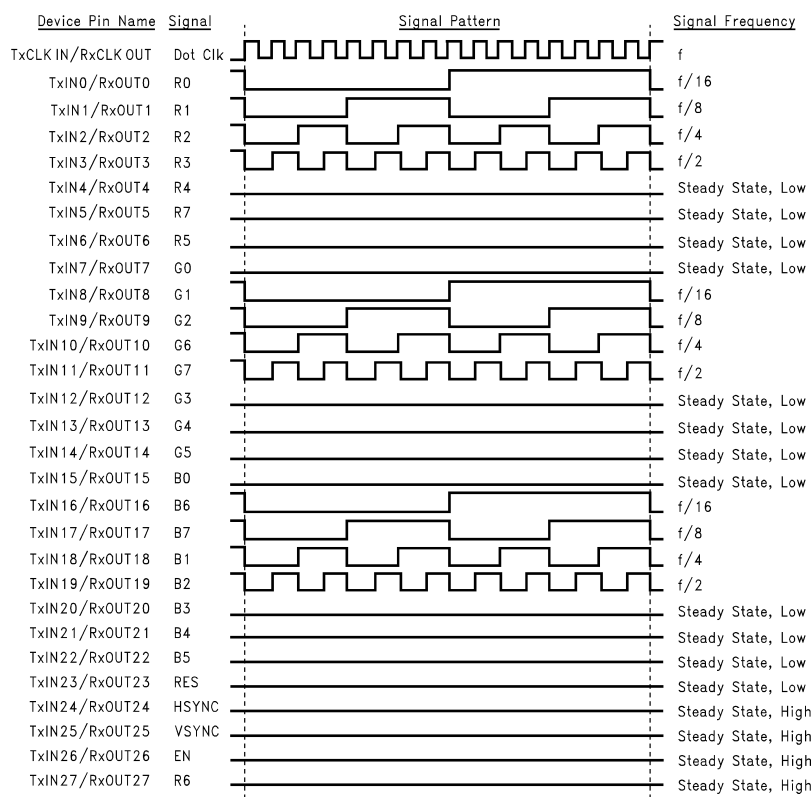
AC Timing Diagrams



- A. The worst case test pattern produces a maximum toggling of digital circuits, LVDS I/O and LVCMOS/LVTTL I/O.
 B. Figure 2 and Figure 3 show a falling edge data strobe (TxCLK IN/RxCLK OUT).

Figure 2. "Worst Case" Test Pattern

AC Timing Diagrams (continued)



- The 16 grayscale test pattern tests device power consumption for a "typical" LCD display pattern. The test pattern approximates signal switching needed to produce groups of 16 vertical stripes across the display.
- Figure 2 and Figure 3 show a falling edge data strobe (TxCLK IN/RxCLK OUT).
- Recommended pin to signal mapping. Customer may choose to define differently.

Figure 3. "16 Grayscale" Test Pattern - DS90C385A

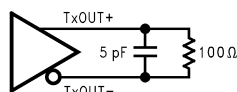


Figure 4. DS90C385A (Transmitter) LVDS Output Load. 5pF is shown as board loading

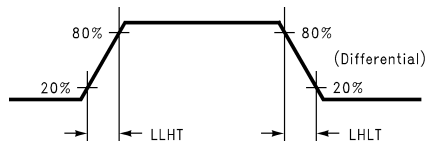


Figure 5. DS90C385A (Transmitter) LVDS Transition Times

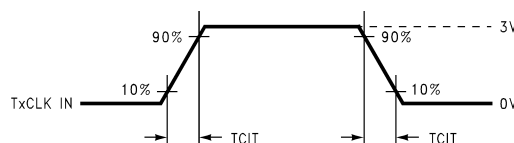


Figure 6. DS90C385A (Transmitter) Input Clock Transition Time

AC Timing Diagrams (continued)

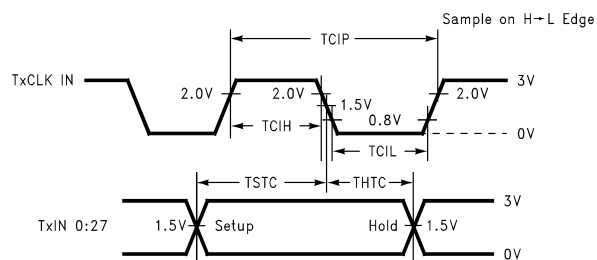


Figure 7. DS90C385A (Transmitter) Setup/Hold and High/Low Times with R_FB pin = GND (Falling Edge Strobe)

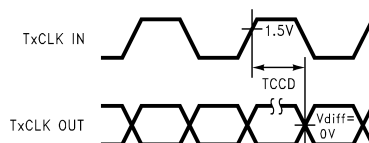


Figure 8. DS90C385A (Transmitter) Clock In to Clock Out Delay with R_FB pin = VCC

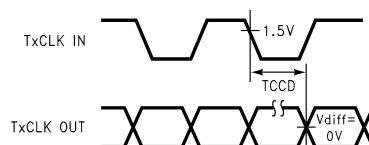


Figure 9. DS90C385A (Transmitter) Clock In to Clock Out Delay with R_FB pin = GND

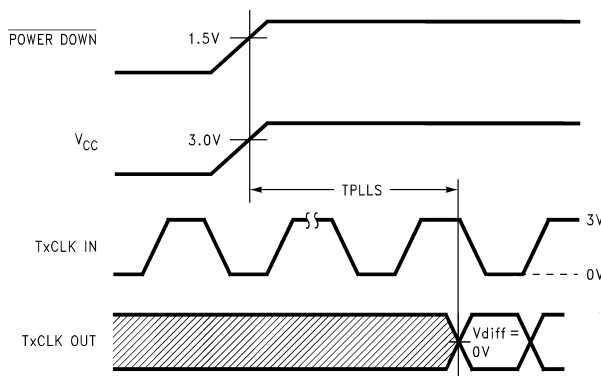


Figure 10. DS90C385A (Transmitter) Phase Lock Loop Set Time

AC Timing Diagrams (continued)

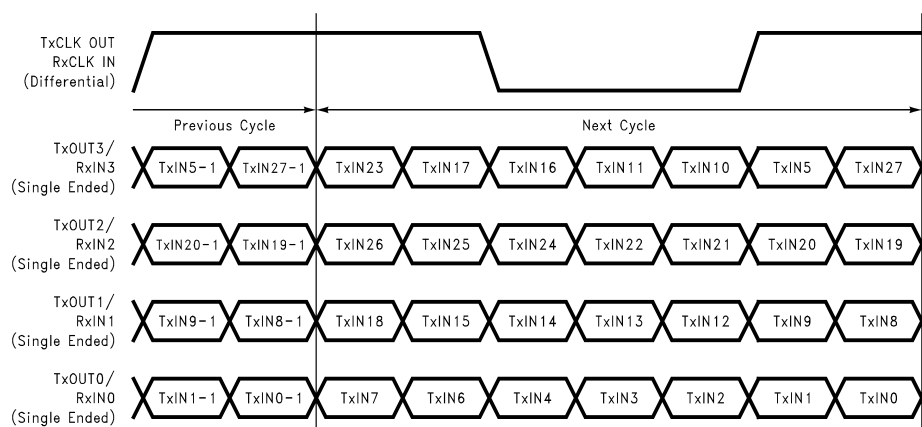


Figure 11. 28 Parallel TTL Data Inputs Mapped to LVDS Outputs - DS90C385A

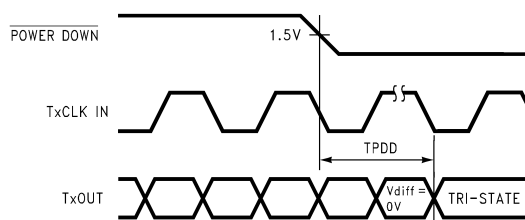


Figure 12. Transmitter Power Down Delay

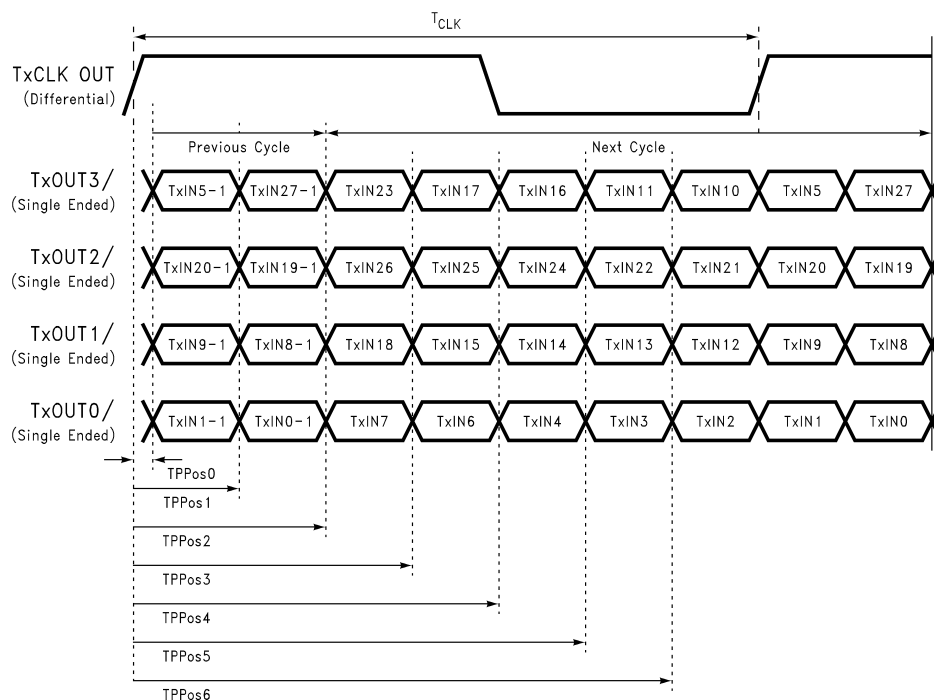
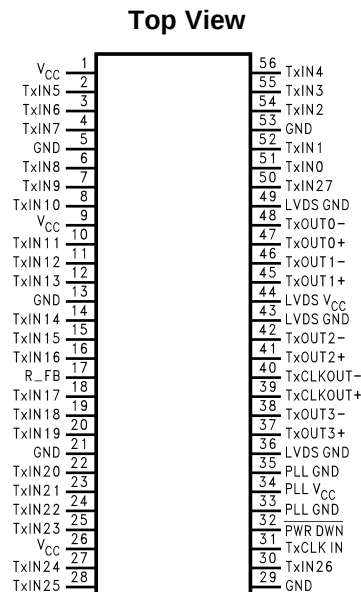


Figure 13. Transmitter LVDS Output Pulse Position Measurement - DS90C385A

DS90C385A DGG (TSSOP) Package Pin Descriptions — FPD Link Transmitter

Pin Name	I/O	No.	Description
TxIN	I	28	LVTTL level input. This includes: 8 Red, 8 Green, 8 Blue, and 4 control lines—FPLINE, FPFRAME and DRDY (also referred to as HSYNC, VSYNC, Data Enable).
TxOUT+	O	4	Positive LVDS differential data output.
TxOUT-	O	4	Negative LVDS differential data output.
TxCLKIN	I	1	LVTTL level clock input. Pin name TxCLK IN.
R_FB	I	1	LVTTL level programmable strobe select (See Table 1).
TxCLK OUT+	O	1	Positive LVDS differential clock output.
TxCLK OUT-	O	1	Negative LVDS differential clock output.
PWR DOWN	I	1	LVTTL level input. When asserted (low input) TRI-STATE the outputs, ensuring low current at power down.
V _{CC}	I	3	Power supply pins for LVTTL inputs.
GND	I	5	Ground pins for LVTTL inputs.
PLL V _{CC}	I	1	Power supply pin for PLL.
PLL GND	I	2	Ground pins for PLL.
LVDS V _{CC}	I	1	Power supply pin for LVDS outputs.
LVDS GND	I	3	Ground pins for LVDS outputs.

Pin Diagram for TSSOP Package


**Order Number DS90C385AMT
DGG Package**

APPLICATION INFORMATION

The DS90C385A is backward compatible with the DS90C385, DS90C383A, DS90C383 in TSSOP 56-lead package, and it is a pin-for-pin replacements.

This device DS90C385A also features reduced variation of the TCCD parameter which is important for dual pixel applications. (See AN-1084)

This device may also be used as a replacement for the DS90CF583 (5V, 65MHz) and DS90CF581 (5V, 40MHz) FPD-Link Transmitters with certain considerations/modifications:

1. Change 5V power supply to 3.3V. Provide this 3.3V supply to the V_{CC} , LVDS V_{CC} and PLL V_{CC} of the transmitter.
2. The DS90C385A transmitter input and control inputs accept 3.3V LVTTL/LVCMOS levels. They are not 5V tolerant.
3. To implement a falling edge device for the DS90C385A, the R_FB pin may be tied to ground OR left unconnected (an internal pull-down resistor biases this pin low). Biasing this pin to V_{CC} implements a rising edge device.

TRANSMITTER INPUT PINS

The TxIN and control input pins are compatible with LVCMOS and LVTTL levels. These pins are not 5V tolerant.

TRANSMITTER INPUT CLOCK/DATA SEQUENCING

Unlike the DS90C385, DS90C(F)383A/363A, the DS90C385A does not require any special requirement for sequencing of the input clock/data and PD (PowerDown) signal. The DS90C385A offers a more robust input sequencing feature where the input clock/data can be inserted after the release of the PD signal. In the case where the clock/data is stopped and reapplied, such as changing video mode within Graphics Controller, it is not necessary to cycle the PD signal. However, there are in certain cases where the PD may need to be asserted during these mode changes. In cases where the source (Graphics Source) may be supplying an unstable clock or spurious noisy clock output to the LVDS transmitter, the LVDS Transmitter may attempt to lock onto this unstable clock signal but is unable to do so due the instability or quality of the clock source. The PD signal in these cases should then be asserted once a stable clock is applied to the LVDS transmitter. Asserting the **PWR DOWN** pin will effectively place the device in reset and disable the PLL, enabling the LVDS Transmitter into a power saving standby mode. However, it is still generally a good practice to assert the PWR DOWN pin or reset the LVDS transmitter whenever the clock/data is stopped and reapplied but it is not mandatory for the DS90C385A.

SPREAD SPECTRUM CLOCK SUPPORT

The DS90C385A can support Spread Spectrum Clocking signal type inputs. The DS90C385A outputs will accurately track Spread Spectrum Clock/Data inputs with modulation frequencies of up to 100kHz (max.) with either center spread of $\pm 2.5\%$ or down spread -5% deviations.

POWER SOURCES SEQUENCE

In typical applications, it is recommended to have V_{CC} , LVDS V_{CC} and PLL V_{CC} from the same power source with three separate de-coupling bypass capacitor groups. There is no requirement on which VCC entering the device first.

Typical Application

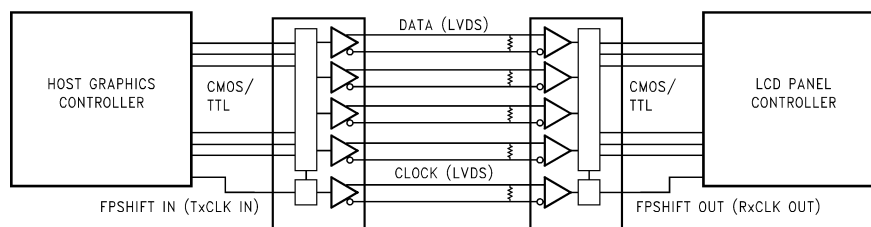


Figure 14. Typical Application

**Table 1. Truth Table – Programmable Transmitter
(DS90C385A)**

Pin	Condition	Strobe Status
R_FB	R_FB = V _{CC}	Rising edge strobe
R_FB	R_FB = GND or NC	Falling edge strobe

REVISION HISTORY

Changes from Revision J (April 2013) to Revision K

Page

- Changed layout of National Data Sheet to TI format [11](#)

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
DS90C385AMT/NOPB	Active	Production	TSSOP (DGG) 56	34 TUBE	Yes	SN	Level-2-260C-1 YEAR	-10 to 70	DS90C385AMT
DS90C385AMTX/ NOPB	Active	Production	TSSOP (DGG) 56	1000 LARGE T&R	Yes	SN	Level-2-260C-1 YEAR	-10 to 70	DS90C385AMT

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS90C385AMTX/NOPB	TSSOP	DGG	56	1000	330.0	24.4	8.6	14.5	1.8	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS90C385AMTX/NOPB	TSSOP	DGG	56	1000	356.0	356.0	45.0

TUBE



*All dimensions are nominal

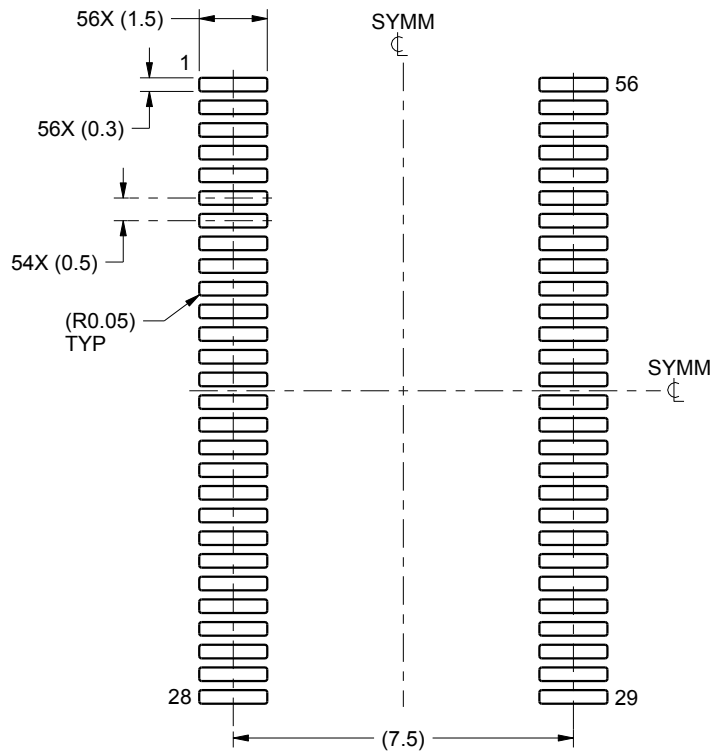
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
DS90C385AMT/NOPB	DGG	TSSOP	56	34	495	10	2540	5.79

EXAMPLE BOARD LAYOUT

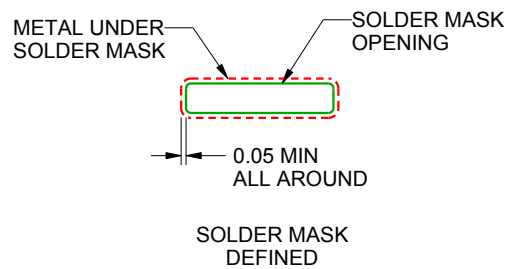
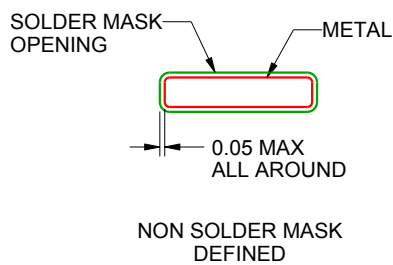
DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4222167/A 07/2015

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

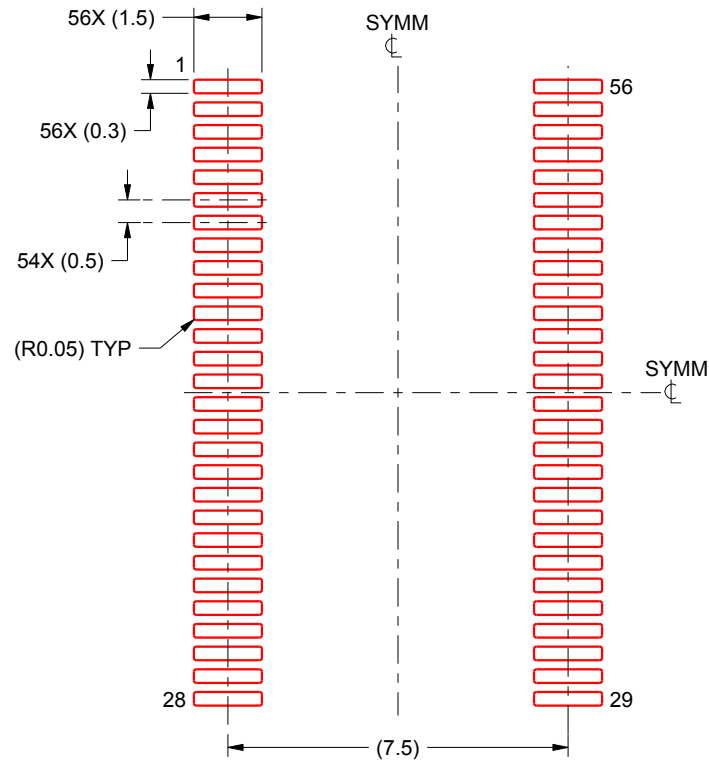
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4222167/A 07/2015

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated